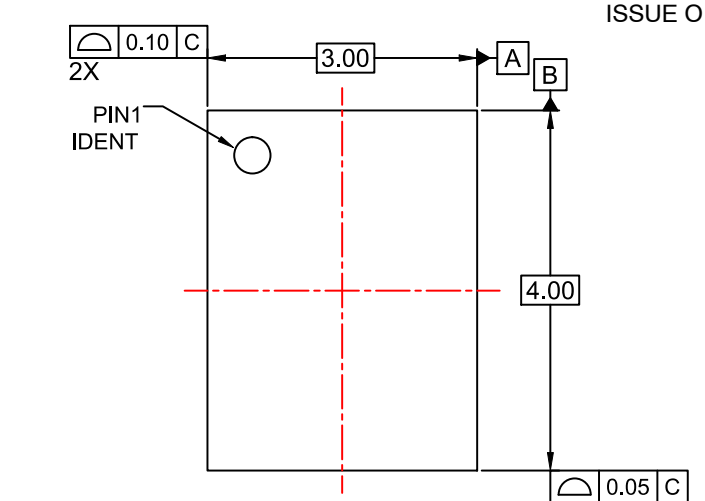
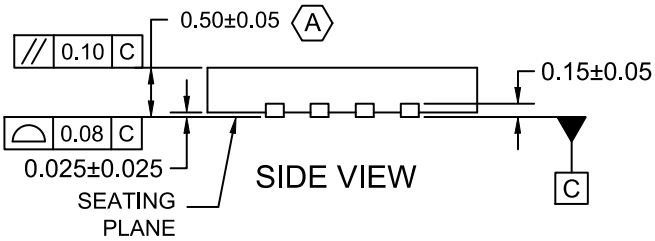
UQFN20 3x4, 0.5P
CASE 523BA
ISSUE O

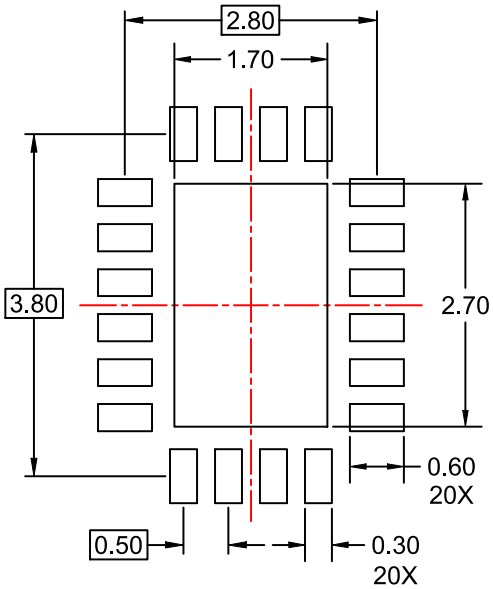
DATE 31 OCT 2016



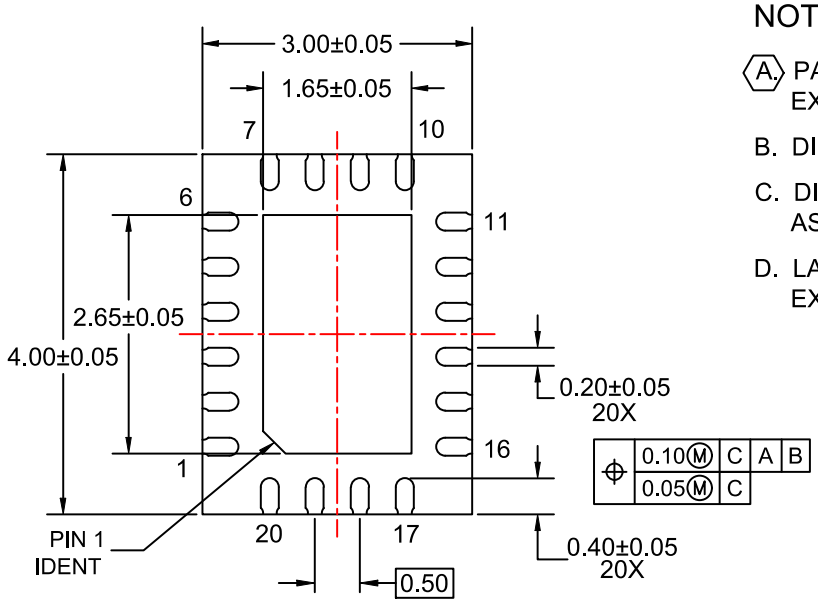
TOP VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN



BOTTOM VIEW

NOTES:

A. PACKAGE CONFORMS TO JEDEC MO-220 EXCEPT WHERE NOTED.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.

D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.

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DESCRIPTION:	**UQFN20 3x4, 0.5P**	**PAGE 1 OF 1**

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